

What Is Claimed Is:

1. A housing for an electronic circuit (4), especially for a control unit, the circuit (4) having a plurality of electrical contacts, which lead to the outside of the housing via individual electronic conductors (2); the housing including a floor plate (3) and a cover (6) as well as at least one seal between the floor plate (3) and the cover (6),
wherein the seal (20) is developed as a single part for sealing a gap between the floor plate (3) and the cover (6), through which the exposed electrical conductors (2) are led, if applicable.
2. The housing as recited in Claim 1,
wherein the floor plate (3), the cover (6) and the conductors (2) are made of the same kind of material, preferably of a metal.
3. The housing as recited in Claim 2,
wherein the floor plate (3) and the cover (6) are made of aluminum.
4. The housing as recited in Claim 2 or 3,
wherein the conductors (2) are made of a copper-containing material, preferably of copper or of a copper alloy.
5. The housing as recited in one of the preceding claims,
wherein the exposed conductors (2) are led in a frame (1) and are positioned fixedly with respect to one another,
the frame (1) being situated between the floor plate (3) and the cover (6), and, because of its specific design, defining the positions and/or the clearances of the floor plate (3), the cover (6) and the exposed conductors (2) relative to one another in the closed housing.

6. The housing as recited in one of the preceding claims, wherein the floor plate (3) and/or the cover (6) or the frame (1) have spacers (11) and/or stops (1a), which in each case are developed and positioned in such a way that they ensure maintaining a predetermined clearance of the conductors (2) from the floor plate (3) or from the cover (6) when the housing is closed.
7. The housing as recited in one of the preceding claims, wherein the floor plate (3) has a depression (3b) for accommodating a part of the seal.
8. The housing as recited in one of the preceding claims, wherein the frame (1) has a recess (14) which, together with the floor plate (3) borders the gap at least in part.
9. The housing as recited in one of the preceding claims, wherein the electrical conductor (2) is developed as a pressed screen strip.
10. A method for sealing a housing for an electronic circuit (4), especially for a control unit, the circuit (4) having a plurality of electrical contacts, which lead to the outside of the housing via individual electrical conductors (2); and the housing including a floor plate (3), a cover (6) and a seal between the floor plate (3) and the cover (6), characterized by the following step:
 - developing the seal in single-part form in a gap between the floor plate (3) and the cover (6), through which the exposed electrical conductors (2) are led, if applicable.
11. The method as recited in Claim 10, wherein the development of the seal (20) takes place

during the assembly of the housing by carrying out the following consecutive steps:

- ~ applying a first sealing compound bed (20-1) to the surface (3a) of the floor plate (3) in the surroundings of the electronic circuit (4) on the floor plate (3),
- ~ putting a frame (1) having the conductors (2) onto the first sealing compound bed (20-1), preferably in such a way that a part of the sealing compound (20-1) wells up between the exposed conductors (2),
- ~ filling up a second part of the clearance space above the conductors (2) using sealing compound to form a second sealing compound bed (20-2), and
- inserting the cover (6) of the housing into the second sealing compound bed (20-2).

12. The method as recited in Claim 11, wherein the cover (6) of the housing is inserted into the second sealing compound bed (20-2) only after the conductors (2) have been bonded to the electronic circuit (4).

13. The method as recited in Claim 10, wherein the development of the seal (20) takes place during the assembly of the housing by carrying out the following steps:

- ~ applying a frame (1), in which the conductors (2) are led and are fixedly positioned with respect to one another, to the floor plate (3) at a predetermined position, and bonding the conductors (2) to the electronic circuit (4),

- filling fluid sealing compound into a groove (18) that is formed by the surface of the floor plate (3) and a recess in the frame (1), and
- closing the housing by the suitable positioning of the cover (6) on spacers (12) and/or stops (1a) of the frame (1), the edge (13) of the cover (6) dipping into the sealing compound (20) in the groove (18).